

Serial No.: 10/791,095

Group Art Unit: 2813

### AMENDMENTS TO THE SPECIFICATION

- Please amend the paragraph in the specification which begins on page 7, line 3, as follows:

The invention continues, Fig. 5, with the formation of ~~the a~~ base for the torch solder bump by electroplating the layers 28, 30 and 32, using ~~the an~~ electroplating process to have each layer have a completely flat top area. The preferred metals for the three indicated and highlighted layers are as follows:

- Please amend the paragraph in the specification which begins on page 7, line 31, as follows:

The structure that is shown in cross section in Fig. 8 is ready for solder reflow, creating a torch bump from the solder ball layer 36 of solder, that is shown in cross section in Fig. 9. The torch bump 36 has a flat bottom area by which it is bonded to the larger flat top area of the layer 32.